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TRANSMITTAL FORM (to be used for all correspondence after initial filing)	Application Number	10/824,723
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	First Named Inventor	L. Pierre deRochemont
	Art Unit	2827
	Examiner Name	TBD
Total Number of Pages in This Submission	Attorney Docket Number	10116-102DIV2

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Date	August 26, 2004

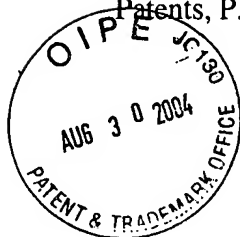
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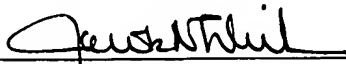
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Jacob N. Erlich
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: L. Pierre deRochemont, et al.

Examiner: TBD

Serial Number: 10/824,723

Group Art Unit: 2827

Filed: April 15, 2004

For: **METHOD OF MANUFACTURE OF CERAMIC COMPOSITE WIRING
STRUCTURES FOR SEMICONDUCTOR DEVICES**

PERKINS SMITH & COHEN LLP
One Beacon Street
Boston, MA 02108
(617) 854-4000

To: Mail Stop Amendment
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P.O. Box 1450
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Sir:

This Information Disclosure Statement (Form PTO-1449) is submitted under 37 CFR 1.97(b)(3).

REMARKS

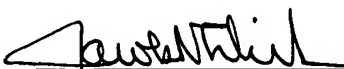
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The following information is presented in the event that a call may be deemed desirable by the Examiner:

JACOB N. ERLICH (617) 854-4000.

Respectfully submitted,
L. Pierre deRochemont, et al., Applicants

Dated: August 26, 2004

By: 
Jacob N. Erlich
Reg. No. 24,338
Attorney for Applicants



FORM PTO-1449
U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO.: 10116-102DIV2

APPLICATION SERIAL NO.: 10/824,723

GROUP ART UNIT: 2827

APPLICANT: L. Pierre deRochemont et al.

EXAMINER: TBD

FILING DATE: April 15, 2004

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PRIORITY DATE: August 29, 1996

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS/SUB -CLASS	FILING DATE IF APPROPRIATE
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					YES	NO
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	WO 98/08672	03/05/98	deRochemont et al.	B32B 3/00		No
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* These patents are representative of the state of the art but published after or less than one year prior to Applicant's priority date. Therefore, if any such item is considered sufficiently relevant by the Examiner to the present invention, its possible "prior art" status against the present invention should be considered individually allowing for the prospect of swearing back or other priority determination.

**These references were disclosed in prior Patent Application No. 09/344,682, filed June 25, 1999, now U.S. Patent No. 6,323,549, and, as such, copies thereof are not included pursuant to the provisions of 37 CFR 1.98(d).

EXAMINER**DATE CONSIDERED**